

Docket No.: WMP-EUP-008

#4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : GOTTFRIED FERBER ET AL. *B L*  
Filed : CONCURRENTLY HEREWITH *6/5/02*  
Title : SEMICONDUCTOR MODULE AND METHOD FOR  
FABRICATING THE SEMICONDUCTOR MODULE



INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,  
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

U.S. Patent 5,517,059 (Eytcheson et al.), dated May 14, 1996;

U.S. Patent 5,938,952 (Lin et al.), dated August 17, 1999;

German published Non-Prosecuted Patent Application DE 42 39 598 A1 (Yamada et al.), dated May 27, 1993, transistor module;

German published Non-Prosecuted Patent Application DE 197 13 656 A1 (Terasawa), dated October 30, 1997, power semiconductor module;

Patent Abstracts of Japan 03 044 954 A (Shigekichi et al.), dated February 26, 1991;

Patent Abstracts of Japan 04 162 641 A (Ryuji), dated June 8, 1992;

Patent Abstracts of Japan 06 254 690 A (Mitsuru), dated September 13, 1994;

Heinzelmann, E.: "Laserschweissen: Der Kniff mit dem Nachjustieren" (laser welding: the trick with the adjusting), TR Transfer, Nr. 17, 1995, pp. 16-19;

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,



For Applicants

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Date: January 24, 2002

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